Solderball Pin[™] Technology







Innovative Interconnections™

bulletin #0312sb

Solderball Pin[™] Technology

Solderball Pin[™] Technology is engineered and widely used on POL (point of load) DC/DC Power applications when a PCB mezzanine design is necessary due to real estate limitations, offering additional thermal dissipation capability via the robust mechanical connection. The Solderball Pin[™] functionally replace the conventional through-hole pins, traditionally used for interconnecting parallel PCBs, and provide a SMT-comapatible solution for mounting the module to the final assembly and the solderball. The internal pin provides a rigid, high conductivity foundation to the module PCB, while the solderball allows a physical adjustment as each solder joint is formed.

Compact configuration and flexibility as a discrete SMT component facilitates adoption into a broad scope of applications, including electronic lighting controls, remote telemetry monitoring, ethernet, fibre channel, storage area networks, automotive, and many other daughter-to-motherboard module-based subassemblies.

The features and key characteristics are summarized as follows: Solder sphere: Provides the attachment and interconnection with the SMT host PCB and compensates for co-planarity variances.

Insulator-seal: Provides a positive location of solder sphere during reflow. It is also the element for vacuum pick-and-place equipment.

Copper Alloy pin: Provides a robust plated-through hole attachment with the PCBSA and determines the stack up height between PCBSA and host PCB.

Solderball Pin[™] Main Features







Solderball Pin[™] Selection Guide

Part N Descr		Qty Per Reel	Tail Configuration	Pin Size Dia Inches/mm	Stack Height Inches/mm	Tail length Inches/mm	Solderball Diameter	RoHs Compliant
Midi Solderball 0.033" [0.84] DiameterTapered Pin. 0.071" [1.8] Diameter Ball								
9-B133	41 AATTA	1,600	Tapered	.033" [0.84]	.100" [2.54]	.034" [0.86]	.071" [1.80]	Tin Lead
9-B133	41AATTT	1,600	Tapered	.033" [0.84]	.100" [2.54]	.034" [0.86]	.071" [1.80]	Yes
9-B133	41BBTTA	1,500	Tapered	.033" [0.84]	.130" [3.30]	.040" [1.02]	.071" [1.80]	Tin Lead
9-B133	41BBTTT	1,500	Tapered	.033" [0.84]	.130" [3.30]	.040" [1.02]	.071v [1.80]	Yes
Midi Solderball 0.059" [1.50] Diameter Tapered Pin. 0.071" [1.8] Diameter Ball								
9-B159	41AATTA	1,500	Tapered	.059" [1.50]	.100" [2.54]	.034" [0.86]	.071" [1.80]	Tin Lead
9-B159	41AATTT	1,800	Tapered	.059" [1.50]	.100" [2.54]	.034" [0.86]	.071" [1.80]	Yes
9-B159	41BCTTT	1,500	Tapered	.059" [1.50]	.130" [3.30]	.045" [1.14]	.071" [1.80]	Yes
Midi Solderball 0.033" [0.84] Diameter Straight Pin. 0.071" [1.8] Diameter Ball								
9-B233	41ADTTA	1,800	Straight	.033" [0.84]	.100" [2.54]	.055" [1.40]	.071" [1.80]	Tin Lead
* 9-B233	41ADTTT	1,800	Straight	.033" [0.84]	.100" [2.54]	.055" [1.40]	.071" [1.80]	Yes
9-B233	41BGTTA	1,300	Straight	.033" [0.84]	.130" [3.30]	.065" [1.65]	.071" [1.80]	Tin Lead
* 9-B233	41BGTTT	1,300	Straight	.033" [0.84]	.130" [3.30]	.065" [1.65]	.071" [1.80]	Yes
9-B233	41CDTTA	1,300	Straight	.033" [0.84]	.150" [3.81]	.055" [1.40]	.071" [1.80]	Tin Lead
9-B233	41CDTTT	1,300	Straight	.033" [0.84]	.150" [3.81]	.055" [1.40]	.071" [1.80]	Yes
9-B233	41DETTA	1,100	Straight	.033" [0.84]	.170" [4.32]	.083" [2.11]	.071" [1.80]	Tin Lead
* 9-B233	41DETTT	1,100	Straight	.033" [0.84]	.170" [4.32]	.083" [2.11]	.071" [1.80]	Yes
Midi Solderball 0.064" [1.62] Diameter StraightPin. 0.071" [1.8] Diameter Ball								
9-B264	41DETTA	1,100	Straight	.064" [1.62]	.170" [4.32]	.083" [2.11]	.071" [1.80]	Tin Lead
9-B264	41DETTT	1,100	Straight	.064" [1.62]	.170" [4.32]	.083" [2.11]	.071" [1.80]	Yes
Power Midi SMT to SMT Solderball 0.070" [1.78] Tierd Pin. 0.041" [1.04] Diameter Ball								
9-00-0	050-1TTT	1,700	Double Tier	.070" [1.78]	.125" [3.18]	SMT	.071" [1.80]	Yes
Mini Solderball 0.038" [0.96] Diameter Straight Pin. 0.041" [1.04] Diameter Ball								
9-B438	41FHTTA	2,000	Straight	.038" [0.96]	.065" [1.65]	.032" [.081]	.041" [1.04]	Tin Lead
* 9-B438	41FHTTT	2,000	Straight	.038" [0.96]	.065" [1.65]	.032" [.081]	.041" [1.04]	Yes
9-B438	41HHTTA	1,700	Straight	.038" [0.96]	.120" [3.05]	.032" [.081]	.041" [1.04]	Tin Lead
9-B438	41HHTAA	1,700	Straight	.038" [0.96]	.120" [3.05]	.032" [.081]	.041" [1.04]	Tin Lead
9-B438	41HHTTT	1,700	Straight	.038" [0.96]	.120" [3.05]	.032" [.081]	.041" [1.04]	Yes
Power Mini SMT to SMT Solderball 0.070" [1.78] Tierd Pin. 0.041" [1.04] Diameter Ball								
9-B970	41H0TTT	1,700	Double Tier	.070" [1.78]	.125" [3.18]	SMT	.041" [1.04]	Yes

* Stocked by Distributors.

Consult Factory for other sizes.

Engineered for Form, Fit & Function

Midi Solderball Pin™

Mini Solderball Pin™



Solder Sphere

dia: 0.071 $\pm 0.004",$ for 0.110" SMT Pad, compensation: 0.020"(.508mm), stack up height up to: 0.195"(4.9mm)

Insulator Disk

94V-0, dia: 0.135", thk: 0.030" Pin to Pin spacing: 0.150" (3.81mm) ctrs. Blue: Pb free, Black: Tin/Lead

Copper Alloy Pin min 0.0001-.0002" Ni and 0.0003-.0005" Sn, plated for 0.041" and 0.072" PCB hole sizes

Solder Sphere

dia: 0.041 \pm 0.004", for 0.075" SMT Pad, compensation: 0.014"(.35mm), stack up height up to: 0.120"(3.05mm)

Insulator Disk

94V-0, dia: 0.090", thk: 0.020" Pin-pin spacing: 0.100" (2.54mm) centers

Copper Alloy Pin

plated for 0.046" PCB hole size or 0.085Ø pad size SMT (2.15mm)

Midi Power Solderball Pin™



Solder Sphere

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- Insulator Disk

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Solder Sphere

Mini Power Solderball Pin[™]

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plated for 0.046" PCB hole size or 0.085Ø pad size SMT (2.15mm)

Mechanical Specifications:

Pin Terminal : Solder Sphere: Packaging: Pick & Place: Configurations: High Conductivity Copper Alloy RoHs Compliant SAC Alloy or Tin/Lead STD 16mm Tape & Reel per Spec EIA-481 Pin Trough Paste Via Standard SMT Equipment email: solderballpin@autosplice.com Lead Free Available

* Consult Factory for Specific Product Performance and Engineering Characteristics.

Solderball Pin[™] Design Guide



SMT Solution to Coplanarity Interconnection

for Power Modules and PCB-based Subassemblies



SMT Board to Board Coplanarity Variation

Solderball Pin[™] Technology employs a highly conductive copper pin that incorporates a solder ball on the end that interfaces to the host PCB, providing additional solder to compensate for coplanarity variation on SMT board to board interconnection.

Features and Benefits:

- Automatic coplanarity compensation*: 0.020"
- High current carrying capability*: 20 amp DC
- Converts through hole device into SMT
- Conducts heat from device to Host PCB



Custom Headers - Solderball Technology





Through Hole To Surface Mount





Surface Mount To Surface Mount



Custom Solutions To Co-Planarity Issues



Customer Specific Configuration



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To obtain a sample kit contact us at: solderballpin@autosplice.com

Authorized Distributors



800.400.7041 contact@heilind.com



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800.325.0534 Contact Casey Donovan cdonovan@keiconn.com

Autosplice Worldwide

USA

Autosplice, Inc. 10121 Barnes Canyon Road San Diego, CA 92121

USA Tel: (858) 535-0077 E-mail: sales@autosplice.com

USA

Autosplice Paramount 7551 Rosecrans Ave. Paramount, CA 90723 USA

Tel: (858) 535-0077 E-mail: sales@autosplice.com

MEXICO

Autosplice Mexico, S. de R.L. de C.V. Cartagena 18960 Plant 1 & 2 El Porvenir, Tijuana, BC 22224 Mexico Tel: 52 664 625 8796

E-mail: sales@autosplice.com

Autosplice Industria E Comercio LTDA Rua Pierre Lafage, 219-Jardim Jaragua CEP 05163-060 Sao Paulo, Sao Paulo State, Brazil Tel: (55 11) 3601 4445 E-mail: conect@autosplice.com.br

() EU

Autosplice Europe GmbH Mühlsteig 2, D-90579 Langenzenn Germany Tel: 49 9101 9014 0 E-mail: info@autosplice.de

LK UK

Autosplice Brittanic Ltd. Delves Road, Heanor Gate Industrial Estate Heanor, Derbyshire DE75 7SJ United Kingdom Tel: 44 1773 713 100 E-mail: info@autosplice.de

JAPAN

Autosplice Japan 3-7-39 Minami Cho, Higashi Kurume Shi Tokyo 203-0031 Japan Tel: 81 424 62 8481 E-mail: info@autosplice.co.jp

KOREA

Autosplice Korea Namdong Industrial Complex 117 Block 2, Lot 686-13, Gojan-Dong, Namdong-Gu, Incheon City, South Korea Tel: 82 32 812 9784 E-mail: info@autosplice.co.kr

SINGAPORE

Autosplice Asia Pte, Ltd. Redhill Industrial Estate 1002 Jalan Bukit Merah, Unit #05-13, Singapore 159456 Tel: 65 6276 8223 E-mail: sales@autospliceasia.com.sg

CHINA

Autosplice Electronics (Dongguan) Ltd. No, 17 Chuang Xin Road 1, Xia Ling Bei Industrial Estate, Liao Bu Town, Guang Dong Province, China Tel : 0769-83525370 E-mail: sales@autosplicechina.com

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Innovative Interconnections™

Inspired Global Solutions™

www.autosplice.com

solderballpin@autosplice.com 🖁